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(54) **SEMICONDUCTOR LIGHT EMITTING  
DEVICE AND METHOD OF  
MANUFACTURING THE SAME**

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**ABSTRACT**

A semiconductor light emitting device includes: a substrate; a light emitting device provided on an upper surface of the substrate; a first pad provided on the upper surface of the substrate; a second pad provided on the upper surface of the light emitting device; a bonding wire connecting the light emitting device to the substrate, the bonding wire including: a first portion connected to and extending in a vertical direction from the first pad; a second portion extending from the first portion and inclined at a first angle relative to the first portion; a third portion extending from the second portion and inclined at a second angle is in a range of from about 125 degrees to about 150 degrees relative to the second portion; and a fourth portion extending from the third portion, inclined at a third angle relative to the third portion, and connected to the second pad; and a seal covering at least one side surface of the light emitting device and sealing the bonding wire on the substrate.

